

SAW Filter datasheet

3.0 x 3.0 x 1.3 mm, SMD

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Features

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- 915 MHz frequency
- Ceramic package for Surface Mounted Technology
- Passband: 26 MHz
- No external matching is required

Applications

- Remote control RF
- Wireless applications:
 o Home appliances
 - Security systems

3.0 x 3.0 x 1.3 mm



Maximum Ratings

Parameter	Min.	Тур.	Max.	Unit
Storage temperature range (T _{stg})	-40		85	°C
Operating temperature range (T_A)	0		70	°C
Maximum Input Power Handling			15	dBm

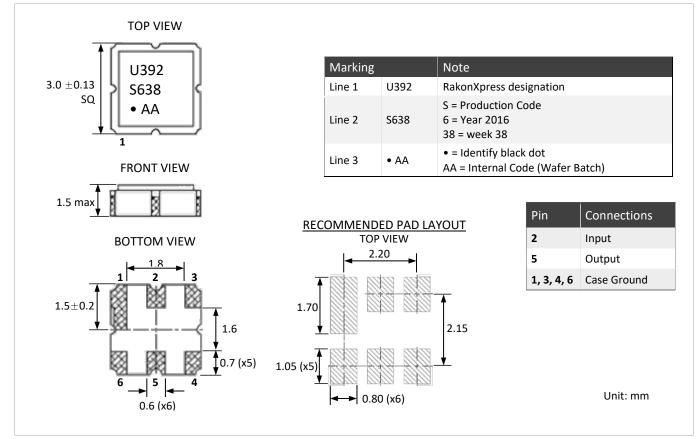
Frequency and Electrical Characteristics (Reference temperature @ 25°C)

Parameter	Min.	Typ. ¹	Max.	Unit
Center frequency (fc)		915		MHz
Bandwidth (BW, passband width)	26.00			MHz
Insertion Loss (IL, 902 – 928 MHz)		2.5	3.3	dB
Amplitude ripple (902 – 928 MHz)		0.5	1.5	dB
Absolute Attenuation				
From 100 to 800 MHz	50	60		
From 800 to 845 MHz	45	50		
From 845 to 880 MHz	35	40		dB
From 947 to 992 MHz	15	20		
From 992 to 1020 MHz	35	40		
From 1020 to 1200 MHz	45	50		
Temperature coefficient of frequency		-30.0		ppm/K
Source impedance ² (Single ended)		50		Ω
Load impedance ² (Single ended)		50		Ω

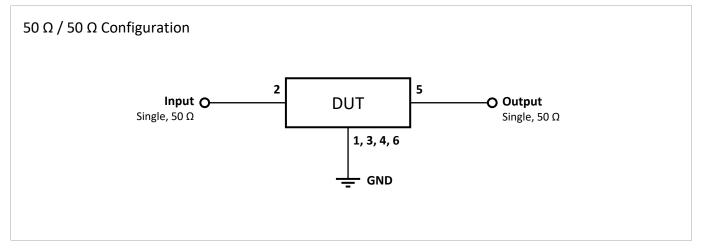
 $^{^1}$ Typical values are nominal performances at room temperature 2 No external matching is required



Model Outline, Pin Connection and Marking



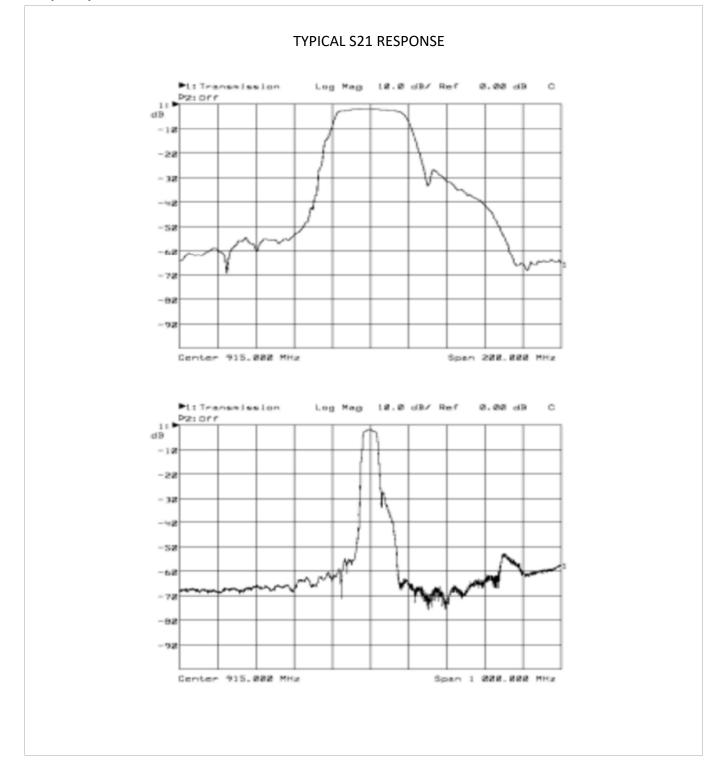
Test Circuit







Frequency Characteristics





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Recommended Reflow Soldering Profile

Temp (Deg C) 180 200 240 260 Time (Sec)

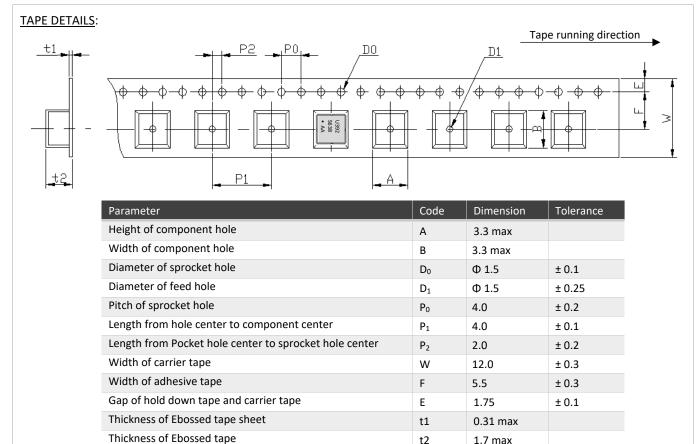
NOTE:

- The components shall remain within the electrical specifications after it soldered on the 1mm thickness PCB board and dipped in the solder at 260 ±5°C during 10 ± 1 seconds.
- The components shall remain within the electrical specifications after it soldered by electric iron, solder at 350 ± 10 °C during 3~4 seconds. Recovery time: 2 ±0.5h.
- Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- Only leads of component may be soldered. Please avoid soldering another part of component.

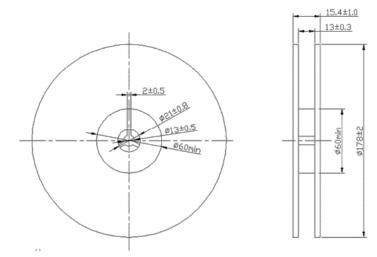


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Tape and Reel Specifications



REEL DETAILS:



NOTE:

- Unit: mm
- Standard Packing Quantity (SPQ) is 3000 pieces/ reel



Reliability Test

Parameter	Test condition / Description
Thermal Shock	The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40° C \pm 3° C, TB=85° C \pm 2° C, t1=t2=30min, switch time \leq 3min & cycle time: 100 times, recovery time: 2h \pm 0.5h.
Temperature Storage	 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C ±2°C for 500 hours, recovery time: 2h ±0.5h. Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C ±3°C for 500 hours, recovery time: 2h ±0.5h.
Humidity test	The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $60^{\circ}C \pm 2^{\circ}C$, and $90^{\sim}95\%$ RH for 500 hours.
Drop test	The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical specifications.
Vibration Fatigue	The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, during 2 hours.
Mechanical Shock	The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s2 , duration 6ms.
Note	As a result of the particularity of inner structure of SAW products, the components can easily be breakdown by electrostatic shock; so it's mandatory to pay attention to ESD protect during the tests.